Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-22. (Canceled)

23. (Previously presented) An EMI/RFI shielding device comprising:

a shaped polymer substrate comprised of a metallized polymer substrate, wherein the shaped polymer substrate is substantially conductive; and

a conductive material on at least one surface of the shaped polymer substrate;

wherein the shaped polymer substrate comprises polyvinyl chloride, polycarbonate, polybutylene terephthalate, or polyethylene terephthalate glycol.

24. (Canceled)

25. (Previously presented) The EMI/RFI shielding device of claim 23 wherein the conductive material comprises aluminum.

26. (Previously presented) The EMI/RFI shielding device of claim 23 wherein the conductive material comprises a substantially uniform thickness over at least one surface of the shaped polymer substrate.

27. (Canceled)

28. (Previously presented) An EMI/RFI shielding device comprising:

a shaped polymer substrate comprised of a metallized polymer substrate, wherein the shaped polymer substrate is substantially conductive; and

a conductive material on at least one surface of the shaped polymer substrate;

wherein the shaped polymer substrate comprises:

a first surface;

a plurality of sidewalls that comprise a first end and a second end, wherein a first end of each of the sidewalls are coupled to the first surface, wherein the sidewalls extend at an angle from the first surface, wherein the first surface and sidewalls define an enclosure portion; and

a peripheral flange coupled to the second end of the sidewalls that extends around the enclosure portion.

29-31. (Canceled)

32. (Previously presented) An EMI/RFI shield comprising:

a thermoformed thin-walled shape formed of a recycled metallized polymeric material, wherein the thermoformed thin-walled shape comprises an inner surface, an outer surface and edges, and wherein the polymeric material comprises polyvinyl chloride, polycarbonate, polybutylene terephthalate, or polyethylene terephthalate glycol; and

a conductive material deposited on at least one of the inner surface and outer surface, wherein the conductive coating comprises a substantially even thickness between 1 micron to 50 microns.

33. (Canceled)

34. (Previously presented) An EMI/RFI shield comprising:

a thermoformed thin-walled shape formed of a recycled metallized polymeric material, wherein the thermoformed thin-walled shape comprises:

an inner surface, an outer surface and edges;

a first surface;

a plurality of sidewalls that comprise a first end and a second end, wherein a first end is coupled to the first surface, wherein the sidewalls extend at an angle from the first surface, wherein the first surface and sidewalls define an enclosure portion;

a peripheral flange coupled to the second end of the sidewalls that extends around the enclosure portion; and

a conductive material deposited on at least one of the inner surface and outer surface, wherein the conductive coating comprises a substantially even thickness between 1 micron to 50 microns.

35-45. (Canceled)

46. (Previously presented) The EMI/RFI shielding device of claim 23 further comprising grinding and re-extruding a metal material along with the polymer substrate.

47-48. (Canceled)

49. (Previously presented) The EMI/RFI shielding device of claim 23 wherein the conductive material comprises copper.

50. (Previously presented) The EMI/RFI shielding device of claim 23 wherein the conductive material comprises nickel.

51-52. (Canceled)